

SOT1705-1

BGA416, plastic, ball grid array; 416 balls; 1 mm pitch; 27 mm x 27 mm x 1.95 mm body

14 August 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA416
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	PBGA-B416
Mounting method type	S (surface mount)
Issue date	29-01-2016
Manufacturer package code	98ARE10523D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	27	-	mm
package width	-	27	-	mm
package height	-	1.95	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	416	-	



BGA416, plastic, ball grid array; 416 balls; 1 mm pitch; 27 mm x 27 mm x 1.95 mm body

2 Package outline

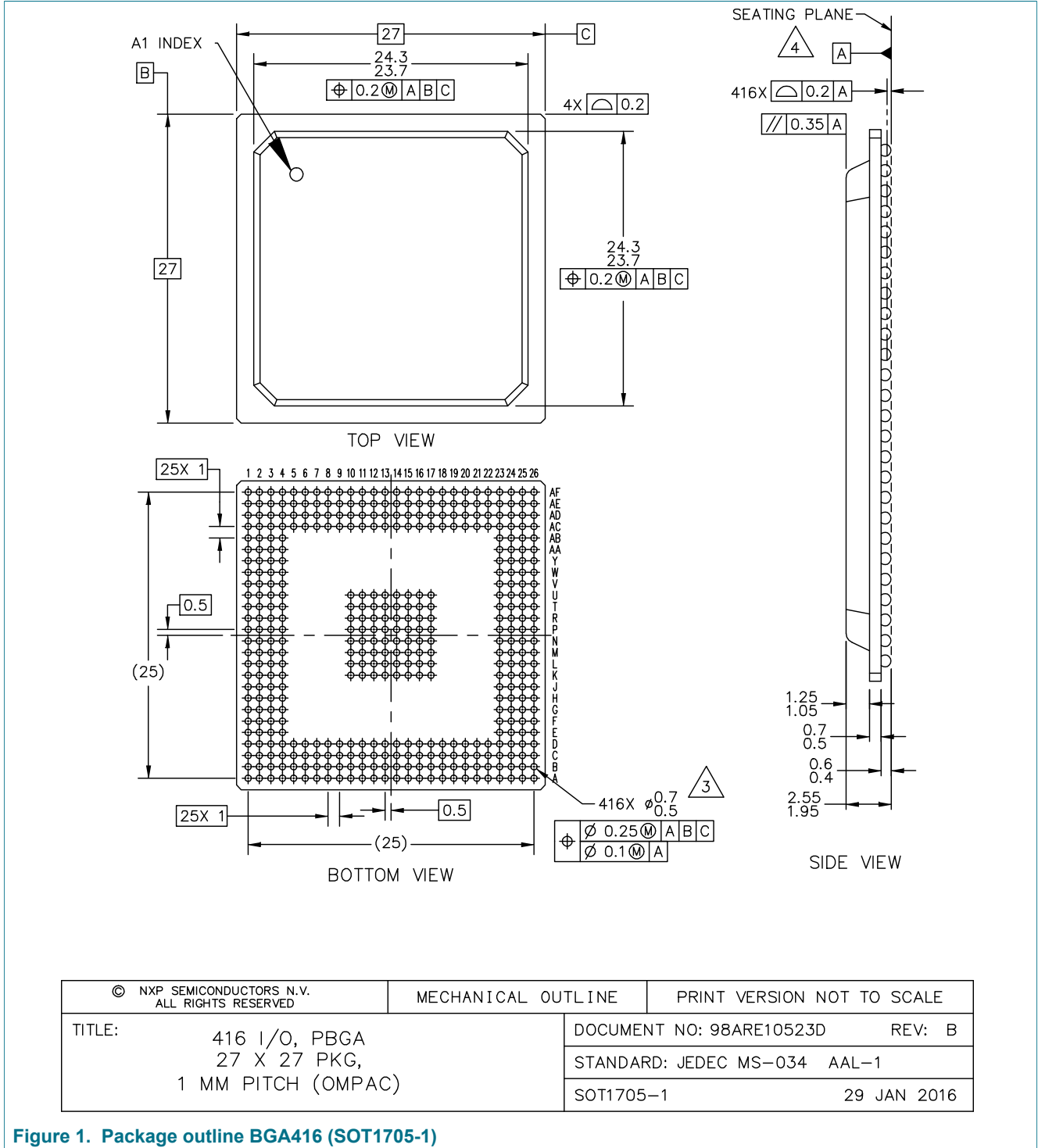


Figure 1. Package outline BGA416 (SOT1705-1)

BGA416, plastic, ball grid array; 416 balls; 1 mm pitch; 27 mm x 27 mm x 1.95 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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TITLE: 416 I/O, PBGA 27 X 27 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARE10523D	REV: B
	STANDARD: JEDEC MS-034	AAL-1
	SOT1705-1	29 JAN 2016

Figure 2. Package outline note BGA416 (SOT1705-1)

3 Legal information

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